MITSUI
KINZOKU

MLS-G

- MLS-G 铜箔系于表面处理制程反转处理铜箔, 其一般特性和 HTE(STD)铜箔无差异,
  具有良好的线路可靠性,适用于内层之细线路及多层增层板用。
- MLS-G has passed through reverse side treatment process. It has the same general properties as HTE(STD) foils with better pattern reliability, ensuring good performance in fine line patterning for inner and build-up layers.
- 具较低的棱线为应用于高速讯号传输板最佳铜箔材料。
  Very low profile of MLS-G makes it an excellent material to apply to high speed transmission board.

用途/Application

- **适用于多层印刷电路板(HDI)**
  /High Density Interconect(HDI)
- **高速讯号传输板**
  /HSD (High speed digital)
- **基地台/伺服器**
  /Base station / Server

结构 /Composition

生产地点 /Production Site

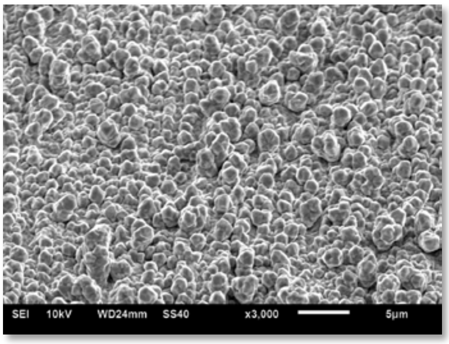
- **台湾 / Taiwan**
- **马来西亚 / Malaysia**

特性代表值/Representative data

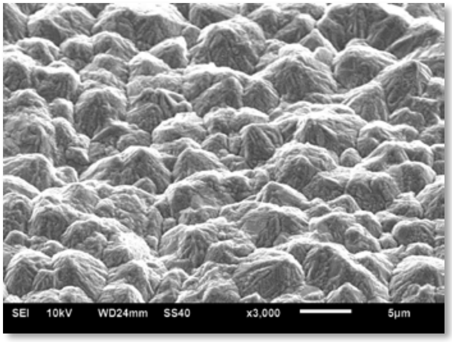
	μm	Rz (μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)
MLS-G	12	3.0	370	6	0.9
	18	3.0	370	8	1.0
	35	3.0	370	16	1.3
	70	3.0	370	19	1.5

※上述表列为代表性数据非保证值。
This is representative data, not guarantee.

处理面/Laminate side



阻剂面/ Resist side



MLS-G

STD. type heavy foil series

- 适用于较高电流设计板材之符合新一代环保要求之电解铜箔。

  MLS-G heavy copper foil comply with environment regulation is suitable for use in high current board design.
- 处理面极低粗度特性极适用于薄板。

  Bonding side with very low roughness is excellent to apply to thin core laminate.
- 铜箔稳定的量产能力, 可充分供应客户需求。

  Our plant has stable capacity for MLS-G to fulfill customer requirements.

用途/Application

- **汽车板**
  /Automotive board
- **与电源供应器**
  /Power supply unit
- **基地台板**
  /Base station

结构 /Composition

生产地点 /Production Site

- **台湾 / Taiwan**

特性代表值/Representative data

	μ m	Rz (μ m)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)
MLS-G	105	3.0	300	15	2.0
	140	3.0	300	15	2.1
	175	3.0	300	15	2.2
	210	3.0	300	15	2.4

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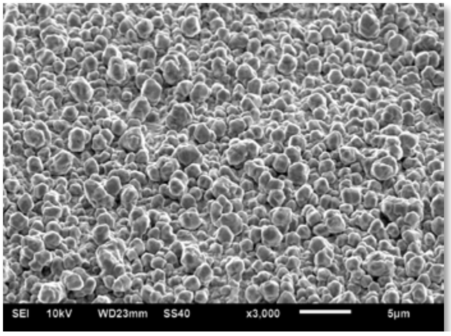
处理面/Laminate side



阻剂面/ Resist side